

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 7,010,723 B2  
DATED : March 7, 2006  
INVENTOR(S) : Pelner

Page 1 of 1

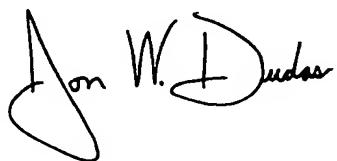
It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page, Item [54] and Column 1, lines 1-3,

Title, delete "**METHOD TO COUPLE INTEGRATED CIRCUIT PACKAGES TO BONDING PADS HAVING VIAS**" and insert -- **METHODS AND APPARATUS TO TEST COMPUTER SYSTEM COMPONENTS** --.

Signed and Sealed this

Thirteenth Day of June, 2006



JON W. DUDAS  
*Director of the United States Patent and Trademark Office*